

Application Serial No: 10/564,114
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the semiconductor chip 20b via electrically conductive portions 17. Thus, similarly to the above-described module 1 according to Embodiment 1 (see ~~FIG. 1~~ FIG. 1A), the signal is transmitted and received between the semiconductor chips 20 included respectively in the semiconductor packages 21a, 21b by radio communication, so that wirings etc. can be omitted so as to allow the miniaturization of the module 2.

[0047] Further, the first radio communication element 16 is constituted independently of the semiconductor chip 20. Consequently, similarly to the above-described module 1 according to Embodiment 1 (see ~~FIG. 1~~ FIG. 1A), the manufacturing cost of the module 2 can be reduced. Moreover, it also is possible to alleviate the influence of the noise due to electromagnetic waves exerted by radio communication carried out by the first radio communication element 16 on an internal circuit of the semiconductor chip 20.

Please amend the following at page 17, lines ¹⁷⁻²²~~17-20~~ of the specification:

Now, a mounted structure according to Embodiment 4 of the present invention will be described with reference to the accompanying drawings. FIG. 6 to be referred to is a schematic sectional view showing the mounted structure according to Embodiment 4. Constituent elements that are the same as those in ~~FIG. 1~~ FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.

Please amend the following at page ²⁰~~18~~, lines ⁹⁻²¹~~17-26~~ of the specification:

Now, as Embodiment 5 of the present invention, the following description is directed to an example of using a combination of a plurality of the modules according to an embodiment of the present invention in a mobile phone. FIG. 7 to be referred to is a perspective view schematically showing a mobile phone in which a plurality of the modules according to an embodiment of the present invention are used. Further, FIG. 8 to be referred to is a perspective view schematically showing the state in which a plurality of the modules according to an embodiment of the present invention are combined and used in the mobile phone shown in FIG. 7. It should be noted that constituent elements other than a first radio communication element in each module are omitted in FIG. 8. Also, constituent elements that are the same as those in ~~FIG. 1~~ FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.